



FXN28N50T Series

Rev.A

General Description

The FXN28N50T uses advanced Silicon's MOSFET Technology, which provides high performance in on-state resistance, fast switching performance, and excellent quality.

These devices can also be utilized in industrial applications such as Low Power Drives SMPS, DC/DC converter, and general purpose applications.

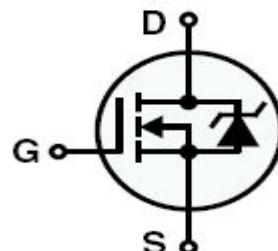
Features

$V_{DS} = 500V$
 $I_D = 28A @ V_{GS} = 10V$
Very low on-resistance
 $R_{DS(ON)} < 0.2\Omega @ V_{GS} = 10V$
100% UIL Tested
100% R_g Tested
150 °C operating temperature



TO-247 Top View

N-channel



Schematic Diagram

Absolute Maximum Ratings ($T_J = 25^\circ C$)

Characteristics	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	500	V
Gate-Source Voltage	V_{GSS}	± 30	V
Continuous Drain Current (1)	I_D	28	A
		23	
		16.7	
Pulsed Drain Current (2)	IDM	112	
Power Dissipation	PD	108	W
		105	
Single Pulse Avalanche Energy (3)	EAS	3020	mJ
Junction and Storage Temperature Range	T_J, T_{stg}	-55~175	°C

Thermal Characteristics

Characteristics	Symbol	Rating	Unit
Thermal Resistance, Junction-to-Ambient (1)	$R_{\theta JA}$	100	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.16	



Electrical Characteristics ($T_J = 25^\circ C$)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BVDSS	ID = 250μA, VGS = 0V	500	540	-	V
Gate Threshold Voltage	VGS(th)	VDS = VGS, ID = 250μA	2	3	4	
Drain Cut-Off Current	IDSS	VDS = 500V, VGS = 0V	-	-	1	μA
Gate Leakage Current	IGSS	VGS = ±30V, VDS = 0V	-	-	±0.1	
Drain-Source ON Resistance	RDS(ON)	VGS = 10V, ID = 14A	-	0.17	0.20	Ω
Forward Transconductance	gfs	VDS = 25V, ID = 14A	-	30	-	S
Dynamic Characteristics						
Total Gate Charge	Qg	VDS = 400V, ID = 28A, VGS = 10V	-	80		nC
Gate-Source Charge	Qgs		-	22	-	
Gate-Drain Charge	Qgd		-	19.2	-	
Input Capacitance	Ciss	VDS = 300V, VGS = 0V, f = 1.0MHz	-	4.2	-	nF
Reverse Transfer Capacitance	Crss		-	0.18	-	
Output Capacitance	Coss		-	1.42	-	
Turn-On Delay Time	td(on)	VGS = 10V, VDS = 300V, ID = 28A, RG = 25Ω	-	25	-	ns
Rise Time	tr		-	38	-	
Turn-Off Delay Time	td(off)		-	96	-	
Fall Time	tf		-	35	-	
Gate Resistance	Rg	f=1 MHz	-	-	-	Ω
Drain-Source Body Diode Characteristics						
Source-Drain Diode Forward Voltag	VSD	IS = 28A, VGS = 0V	-	1.0	1.5	V
Body Diode Reverse Recovery Time	trr	IF = 28A, dI/dt = 100A/μs	-	538		ns
Body Diode Reverse Recovery Charg	Qrr		-	4.2		μc

Note

1. Surface mounted FR-4 board by JEDEC (jesd51-7)
2. Pulse width limited by T_{Jmax}
3. EAS is tested at starting $T_j = 25^\circ C$, $L = 10.5mH$, $I_{AS} = 28A$, $V_{GS} = 10V$ $VDD=50V$



Typical Characteristics (T_j=25C Noted)

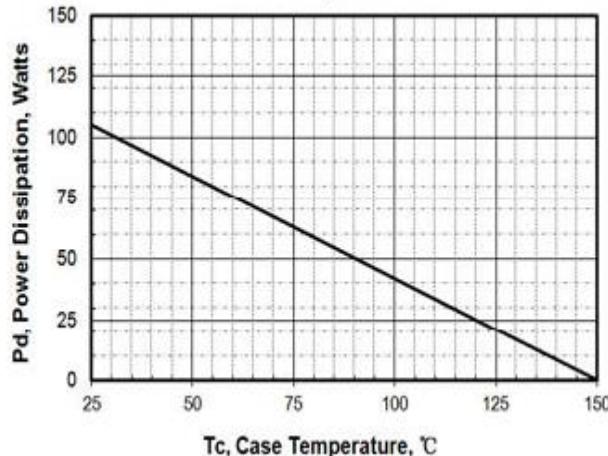


Figure 1. MAX.Power Dissipation VS Casse Temperature

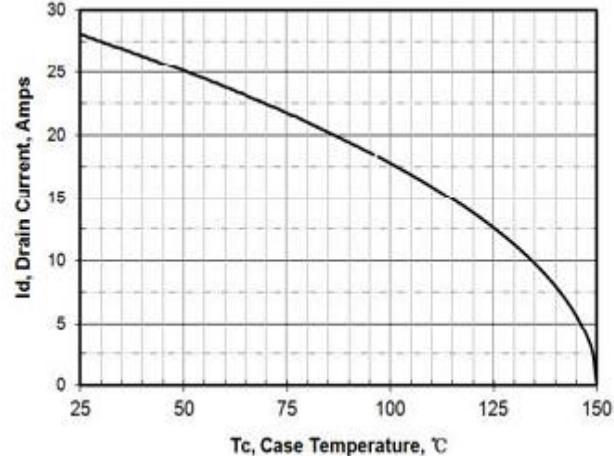


Figure 2. Maximum Continuous Drain Current vs Tc

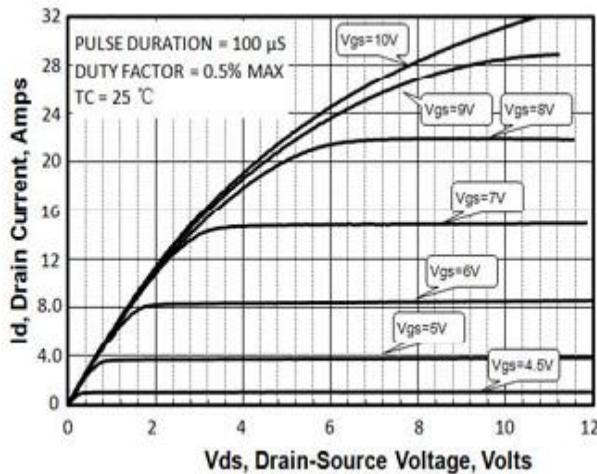


Figure 3. Output Characteristics

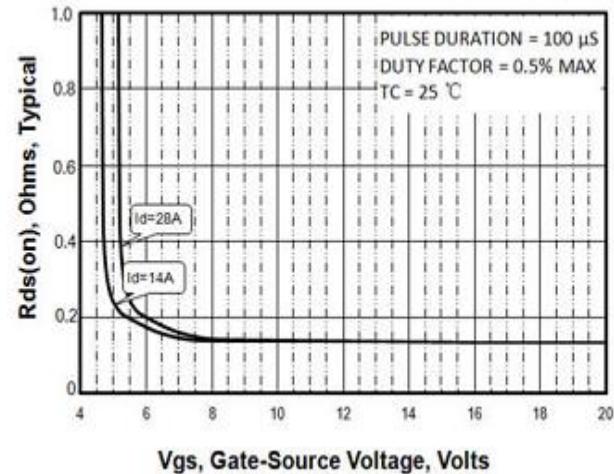


Figure 4. Rdson VS Gate Voltage

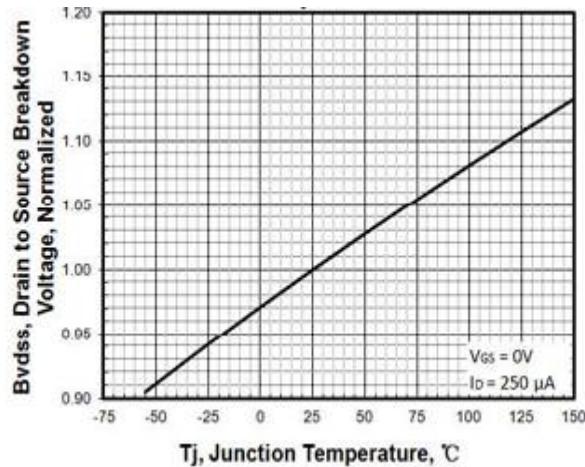


Figure 5. Breakdown Voltage VS Temperature

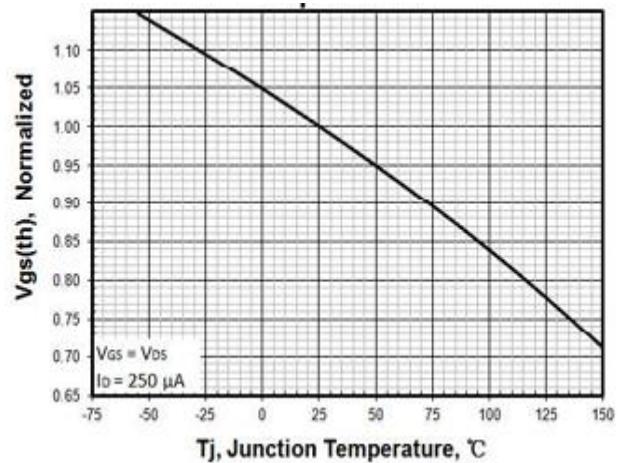


Figure 6. Threshold Voltage VS Temperaturre

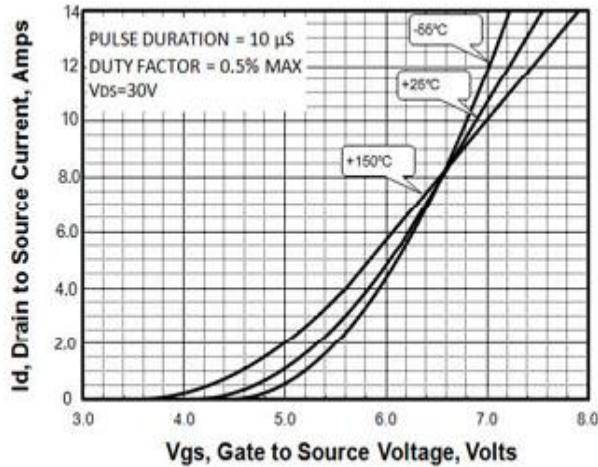


Figure 7. Transfer Characteristics

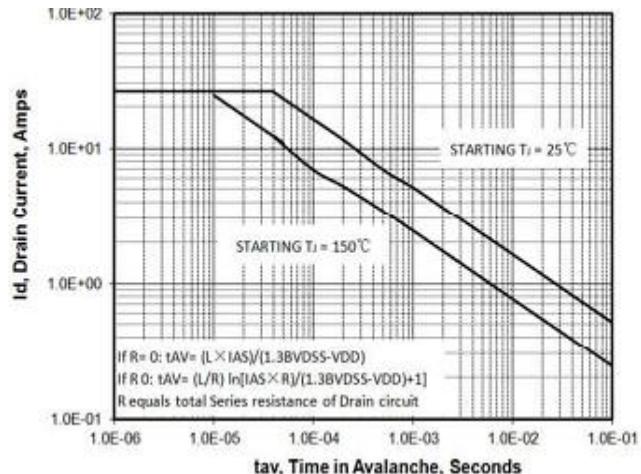


Figure 8. Unclamped Inductive Switching Capability

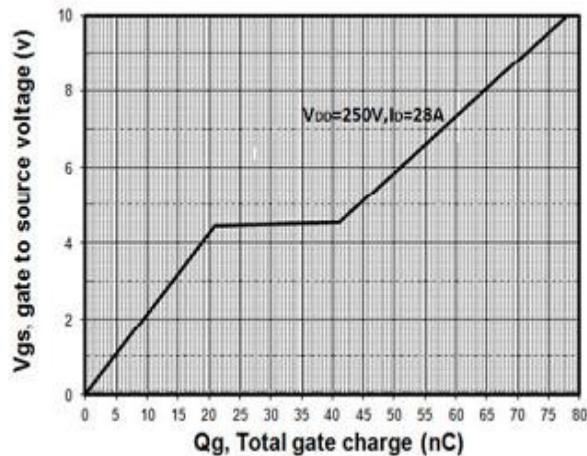


Figure 9. Typical Gate Charge

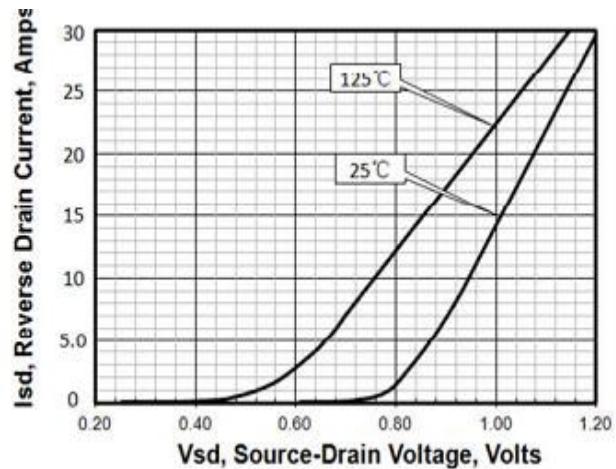


Figure 10. Body Diode Transfer characteristics

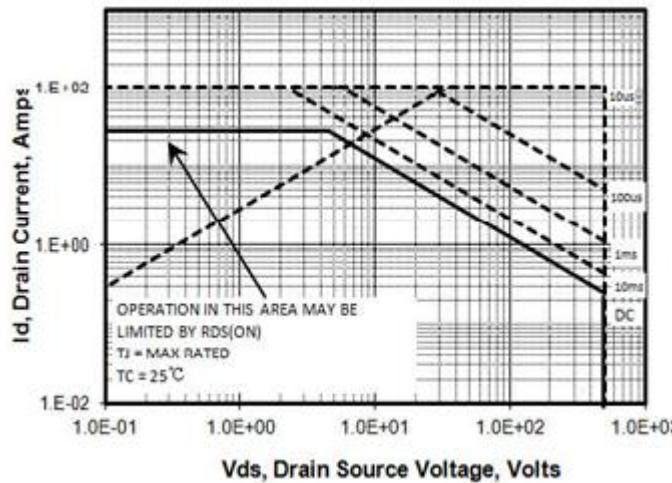


Figure 11. Maximum safe Operating Area

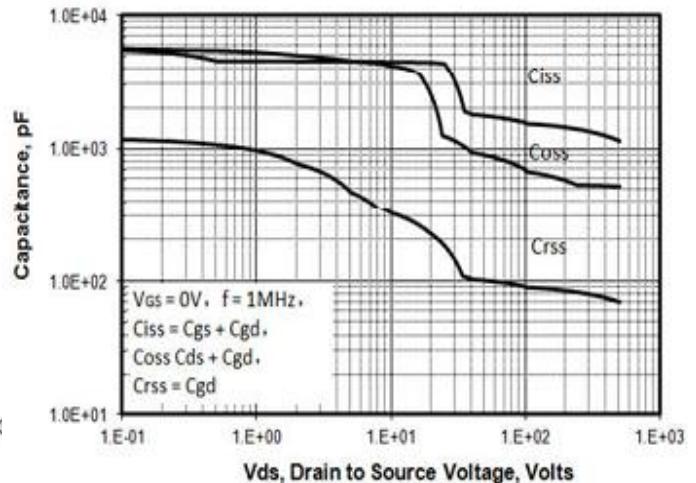
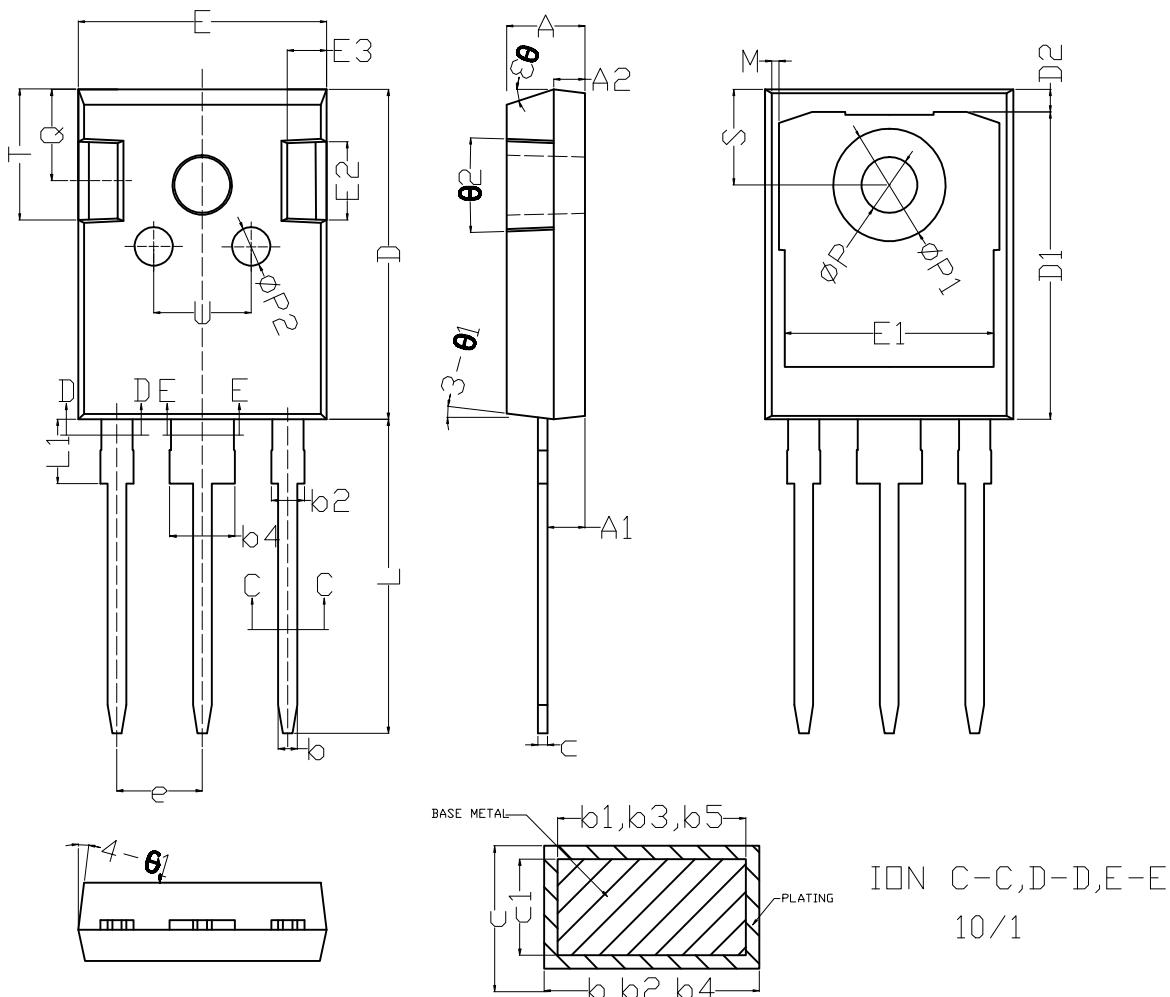


Figure 12. Capacitance VS Vds



TO-247 Package Information



COMMON DIMENSIONS

SYMBOL	MIN	NOM	MAX
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16	1.21	1.26
b1	1.15	1.20	1.25
b2	1.95	2.10	2.15
b3	1.94	2.09	2.14
b4	3.10	3.15	3.20
b5	3.09	3.14	3.19
c	0.59	0.61	0.66
c1	0.58	0.60	0.65
D	20.90	21.00	21.10
D1	16.25	16.55	16.85
D2	1.05	1.20	1.35
E	15.70	15.80	15.90
E1	13.10	13.30	13.50
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.44BSC		
L	19.80	19.92	20.10
L1	—	—	4.30
M	0.35	0.50	0.75
P	3.50	3.60	3.70
P1	7.00	7.20	7.40
P2	2.40	2.50	2.60
Q	5.60	5.80	6.00
S	6.05	6.15	6.25
T	9.80	10.00	10.20
U	6.00	—	6.40
θ1	5°	7°	9°
θ2	3°	5°	8°
θ3	13°	16°	19°